



DRESDEN 2018

## 7<sup>th</sup> ELECTRONICS SYSTEM-INTEGRATION TECHNOLOGY CONFERENCE

September 18<sup>th</sup>-21<sup>st</sup> 2018

### CALL FOR EXHIBITORS

*THE SINGLE LARGEST SEMICONDUCTOR PACKAGING CONFERENCE IN EUROPE*

It is our pleasure to announce the 7<sup>th</sup> ESTC Conference, the premier European scientific conference event in the field of microelectronics packaging and system integration. The conference will be held from 18<sup>th</sup> to 21<sup>st</sup> of September 2018. This international event brings together both academics as well as the industry leaders to present and discuss state-of-the-art and the future trends in packaging and integration technologies. ESTC provides a perfect opportunity to learn about the latest developments in those fields. Save the date right now! This major event only takes place once every 2 years. ESTC is supported by IEEE-EPS in association with IMAPS-Europe. The 2018 conference continues the line of prestigious events since the birth of ESTC 2006 in Dresden, followed by Greenwich, Berlin, Amsterdam, Helsinki and Grenoble every even year.

Read more about the whole history at [www.estc-conference.net](http://www.estc-conference.net)

#### AUDIENCE

ESTC conference provides you an unique opportunity to exhibit your products or services to more than 400 engineers and managers from all areas of the microelectronics and system integration industry. These include materials & processes for semiconductor packaging, assembly and interconnect technologies, test & other equipment, simulation and other software tools, wafer bumping services, market research and research centers.

To meet the audience interests best the exhibition will be focus on and organized matching the application clusters:

- *Automotive,*
- *Manufacturing,*
- *Testing & Sensors and*
- *Simulation.*

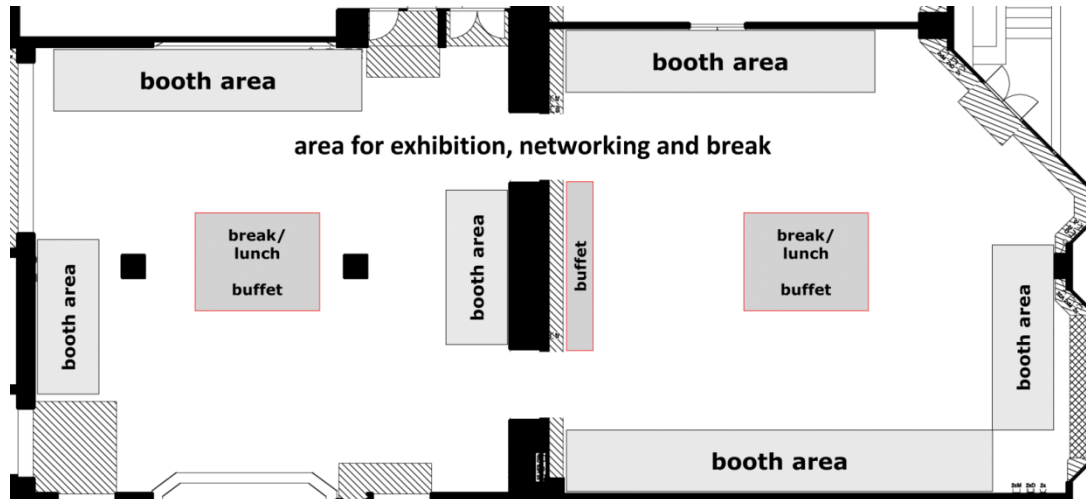
#### VENUE

The conference will be located at the Westin Bellevue Hotel in the center of Dresden Germany on ground floor of the building. The venue is easy to access via public transportation, railway, car, or arrival by plane. Scan the QR for more information.



## EXHIBITION AREA

All technical sessions as well as breaks and catering breaks and the exhibition – 420 m<sup>2</sup> space – will take place in the same area. The exhibition area will be the focus point for the conference attendees all time.



## EXHIBITION SCHEDULE

ESTC conference is a three day event, where the first half of the day is dedicated to technical short courses and the second half for invited keynotes and technical parallel sessions. The second and third days are fully dedicated to technical sessions and keynotes, exhibition. The exhibition schedule of the three days will be as follows.

### Tuesday September 18

10:00 - 12:00 Setup  
12:00 - 18:00 Exhibition

### Wednesday September 19

08:00 - 18:00 Exhibition

### Thursday September 20

08:00 - 12:00 Exhibition  
12:00 - 16:00 Dismantling

## BOTH EQUIPMENT

Booths are available with 4 m<sup>2</sup> (2x2) size at a price of 2000 €. Booths with 6 m<sup>2</sup> (3x2) are available on request at a price of 2800 €.

- **Structure:** Frame construction with aluminum profile (white). Internal separation panels hard masonite coated white. Carpet on the whole booth surface.
  - **Height under ceiling:** >3 m - **Wall height:** 2.50 m - **Power:** 1 distribution board 3 kW - **Lighting:** 3 spots
  - **Furniture:** 1 rectangular table 120x70 cm<sup>2</sup> or 1 showcase 100x50x100 cm<sup>3</sup> and 1 square table 80x80 cm<sup>2</sup>, 2 chairs, 1 waste paper box, 1 company sign on booth front (30 letter)
- Additional furniture:** All extra furniture orders are made by organization, e. g.:



brochure rack, 3 shelves A4



showcase, 100x50x100 cm<sup>3</sup>

- 2 full **conference access** with ordering a booth (only for company staff, no accommodation included, special conference rate for Westin Bellevue accommodation available when booking via ESTC organizers).

## CONTACT

Karsten Meier: Tel +49 (0) 351 463 36594, Fax +49 (0) 351 463 37035, Email [exhibition@estc-conference.net](mailto:exhibition@estc-conference.net)

## IMPORTANT DATES

- Website open for abstract submission: December 1<sup>st</sup>, 2017
- Abstract submission deadline: February 15<sup>th</sup>, 2018
- Notification of acceptance: March 30<sup>th</sup>, 2018

### General Chair

Karlheinz Bock  
Technische Universität Dresden,  
Germany

### Executive Chair

Thomas Zerna  
Technische Universität Dresden,  
Germany

### Technical Program Chair

Steffen Kröhnert  
Amkor Technology, Inc.,  
Portugal

### Exhibition Chair

Karsten Meier  
Technische Universität Dresden,  
Germany

# EXHIBITOR REGISTRATION FORM

Please, send back to Karsten Meier: Tel +49 (0) 351 463 36594, Fax +49 (0) 351 463 37035, Email [exhibition@estc-conference.net](mailto:exhibition@estc-conference.net)

## EXHIBITOR (Please write in CAPITAL LETTERS)

Company Name: \_\_\_\_\_  
Street: \_\_\_\_\_  
ZIP: \_\_\_\_\_ City: \_\_\_\_\_ Country: \_\_\_\_\_  
Tel: \_\_\_\_\_ Email: \_\_\_\_\_  
Booth Manager Name: \_\_\_\_\_ First Name: \_\_\_\_\_  
Email: \_\_\_\_\_

## ADDRESS INVOICE (if different from above)

Company Name: \_\_\_\_\_  
Street: \_\_\_\_\_  
ZIP: \_\_\_\_\_ City: \_\_\_\_\_ Country: \_\_\_\_\_  
Tel: \_\_\_\_\_ Email: \_\_\_\_\_  
Booth Manager Name: \_\_\_\_\_ First Name: \_\_\_\_\_  
Email: \_\_\_\_\_

## BOOKING CONDITIONS

- Booth of 6 m<sup>2</sup> 2800 €
- Booth of 4 m<sup>2</sup> 2000 €

I confirm booth reservation.

TOTAL BOOTH \_\_\_\_\_ €

## ADDITIONAL FURNITURE CATALOGUE

- One brochure rack  
Price: 60 €
- One showcase  
Price: 220 €

## PAYMENT CONDITIONS

**30% deposit to pay at booth reservation:** \_\_\_\_\_ € Total

**Final payment on June 15<sup>th</sup> 2018** \_\_\_\_\_ € Total

Booth reservation will be confirmed only at first account reception. In case of cancellation, the 30% account will be kept.

